EDITORIAL

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Fourth Asian Conference on Mechanics of Functional Materials and Structures (ACMFMS 2014)

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This special issue consists of the papers selected from the Proceedings of the Fourth Asian Conference on Mechanics of Functional Materials and Structures (ACMFMS 2014) which was held at Nara, Japan, and organized and hosted by the Osaka Institute of Technology (OIT), Japan, during October 10–13, 2014. ACMFMS 2014 is the successor of the First, the Second and the Third conferences held at Matsue, Japan, in 2008, Nanjing, China, in 2010 and New Delhi, India, in 2012, respectively.

The aim of ACMFMS series is to provide a forum for researchers and academics, particularly from East Asia and the neighboring regions, to interact, exchange ideas and establish relationships, with a view to future cooperation and subsequent development of research in theoretical and applied mechanics of solids. Those who are young and eager to gain their experience and knowledge are especially encouraged to participate and use this opportunity to establish a network with each other.

The conference statistics show that we received 177 submissions from 19 countries/regions, reflecting the growing interest in the conference. Among the accepted submissions, the proceedings contained 162 papers covering Mechanics of Functional and Intelligent Materials, Mechanics of Functional and Smart Structures, Structural Health Monitoring, Elasticity, Plasticity, Fracture and Damage Mechanics, Impact Mechanics and Dynamic Material Behavior, Contact Mechanics, Solid–Fluid Interaction and Mechanics of Wood and Wood Based Materials. The conference consisted of one special lecture, four keynote lectures, 13 organized sessions, 5 general sessions and a poster session. The organized sessions had 131 oral presentations, and the general sessions had 26 oral presentations.

The program committee of ACMFMS 2014 selected 16 papers based on the recommendation of two reviewers of the four-page proceedings papers. As the guest editor, I invited the authors of the selected 16 papers to submit a full-length paper to the special issue of Acta Mechanica. The full-length submissions were then reviewed by two or more referees in the subject area selected from across the globe. Finally, 14 papers have passed through the rigorous review process and have been accepted for this special issue.

I would like to express my heartfelt gratitude to the Editorial Board of the ACTA MECHANICA headed by Prof. Hans Irschik for dedicating this precious issue for ACMFMS 2014, and bestowing the trust on me for editing it. I also extend my sincere thanks to all the authors for their fine contributions and to the large number of reviewers for sparing their valuable time in providing sincere and critical reviews. Special note of gratitude goes to Prof. Ryuusuke Kawamura at the University of Miyazaki, Japan, who actively took the chair of the program committee of ACMFMS 2014 and Prof. Yasutomo Uetsuji at the Osaka Institute of Technology, Japan, who devotedly served as the secretary of ACMFMS 2014. I hope and believe that the ACMFMS community will grow even stronger with each successive conference. The next ACMFMS 2016 will be held in the beautiful city of Shanghai, China, during October 14–17, 2016, at which I look forward to seeing a large attendance again.

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